COMPUTEX TAIPEI InnoVEX
May 20 - 23, 2025 TaiNEX 1 & 2
DAY 2

COMPUTEX DAILY

Organizers: TAITRA TCA
Publisher: TAITRA
Publication Sponsor: 印象臺灣 eye on TAIWAN Media

thermaltake

Taipei Nangang
Exhibition Center Hall 1
4th Floor #N0102

BEYOND IMMERSION

Scan QR Code to learn more

SUPERMICRO

BE FIRST

with Rack-Scale AI

End-to-End Building Blocks for Data Centers of the Future
with AMD, Intel® & NVIDIA

Learn More at www.supermicro.com

SUPERMICRO® AMD intel® NVIDIA

COMPUTEX 2025 Opening Ceremony

COMPUTEX 2025 Grand Opening Forging Global Partnerships to Lead AI-Driven Living

COMPUTEX 2025 officially kicked off today at the Taipei Nangang Exhibition Center Halls 1 and 2, running through May 23. Under the theme “AI Next,” COMPUTEX 2025 features 1,400 exhibitors from 34 countries, using 4,800 booths across 80,000 square meters of exhibition space. The grand opening ceremony invites President Lai Ching-te, Secretary-General to the President Pan Men-an, Premier Cho Jung-tai, TAITRA Chairman James Huang, TCA Chairman Paul Peng, marking the start of this year’s most anticipated global technology event.

President William Lai

President Lai highlighted, “Over 90% of the world’s advanced semiconductor wafers are produced in Taiwan, supporting the prosperity of global industries. The government is proactively formulating trade and economic cooperation policies to deepen connections with countries worldwide. Our goal is to build a Taiwan-centered alliance for a democratic semiconductor supply chain—one that fosters a secure, trustworthy, and open global technology network.”

TAITRA Chairman James Huang added,“AI has crossed the Turing Boundary—gaining memory and evolving closer to human-like intelligence. This marks a deeper transformation that connects hardware and software, and unites humans with artificial intelligence. Taiwan stands at the center of this revolution, leveraging its strengths in semiconductors, innovation, and advanced computing to lead the AI era.”

TCA Chairman Paul Peng said, “Taiwan holds three major competitive advantages in the AI era: a robust semiconductor supply chain, strong capabilities in hardware-software integration, and practical solutions to address aging populations and labor shortages—demonstrating industrial resilience.”

From Chips to Systems: Demonstrate the Power of Taiwan’s AI Ecosystem

As a premier global exhibition for AI and startups, COMPUTEX 2025 centers around three major themes: AI& Robotics, Next-Gen Tech and Future Mobility. This year introduces

TCA Chairman Paul Peng

TAITRA Chairman James Huang

NVIDIA's MGX Ecosystem on dispay at COMPUTEX 2025 yesterday at the Nangang Exhibition Hall 2

President William Lai and participating guests tour COMPUTEX 2025.

two new specialized zones: the AI Services Technology Zone and the Robotics & Drones Zone.

Leading exhibitors include Acer, ADATA, Advantech, ASRock, ASUS, Auras, BenQ, Chenbro, GIGABYTE, Delta, ECS, G.SKILL, Foxconn, Innodisk, Intel, Inventec, KIOXIA, LITEON, MediaTek, MSI, NVIDIA, MiTAC, Pegatron, and PGW, showcasing a full spectrum of AI innovation from hardware to application.

Celebrating the 10th anniversary of InnoVEX, the show welcomes 450 startups from 24 countries, a 12.5% growth from last year. Ten national pavilions—representing Belgium, Brazil, France, Australia, Japan, Thailand, the Philippines, Israel, Poland, and the Czech Republic—underscore the show's global innovation reach.

Notable incubators and accelerators such as NVIDIA Inception Program, Garage+, StarFab, Taipei Exchange, Edge AI Foundation, and Interlink are also participating with startup teams, igniting creative sparks across the show.

Keynotes and Forums: Advancing the AI 2.0 Era

COMPUTEX 2025 features keynote speeches from the world's most influential tech leaders, including NVIDIA CEO Jensen Huang, Qualcomm President and CEO Cristiano Amon, Foxconn Chairman Young Liu, MediaTek Vice Chairman and CEO Dr. Rick Tsai, and NXP Executive Vice President Jens Hinrichsen, sharing the latest breakthroughs and forward-looking industry insights.

The COMPUTEX Forum has also been fully upgraded, themed "AI in Action." This year's lineup features 13 heavyweight speakers from across the AI ecosystem, including Google DeepMind, NVIDIA, Texas Instruments, Advantech, Arm, Intel, Adobe, Cadence, bp Castrol, Infineon, Seagate, Schneider Electric, and Compal, offering in-depth discussions on critical issues shaping the AI supply chain.

Diverse Events Enhance the Visitor Experience

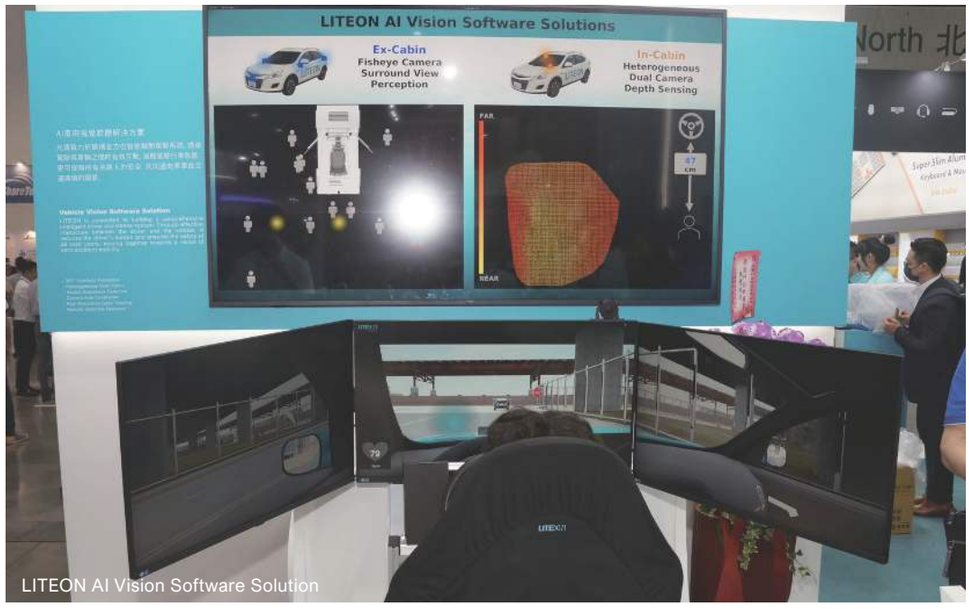
In addition to 1-on-1 sourcing meetings, guided tours, ESG GO! initiative, and Pitch Contest, TAITRA is also launching creative events, including Tech'em High, a collaborative nightlife event with KOR Taipei, and the Hospitality Lounge curated by Taiwan Stock Exchange Corporation and GQ Taiwan—blending business networking with lifestyle and capital market integration.

COMPUTEX and InnoVEX 2025 run from May 20 to 23 at the TaiNEX 1 & 2. Industry professionals are warmly invited to explore the latest breakthroughs in AI, experience cutting-edge technologies, and connect with global leaders shaping the future of innovation. For more information: https://www.computextaipei.com.tw/en/index.html.For more exhibition information:

COMPUTEX: https://www.computextaipei.com.tw/en/index.html
InnoVEX: www.innovex.com.tw

Biaxial Technology Revolution 2025: Smart Mobility, HMD Reshape Industry Landscape

The priorities in global technology development in 2025 are Smart Transportation Ecosystem and Head-mounted Display (HMD) Technology. These two critical axes intertwine and evolve quickly. The former embodies future mobility, while the later explores the border of sensational experience. With artificial intelligence at the core of their development and the application of sensors, displays, power management and software platforms, systematic transformation is taking place globally in sectors such as Information and Communication Technology (ICT), production and manufacture, cloud service and city governance.



LITEON AI Vision Software Solution

The Future of AI-driven Is Taking Shape

To solve traffic congestion and reduce accidents, smart vehicles are crucial. Using various sensors to collect environmental information, computers can assist in driving decisions. This is a capability that is already seen in current autonomous driving technologies. Most new cars on the market now feature Level 2 automated driving assistance (also known as Partial Driving Automation). This level, which involves the use of advanced driver assistance systems (ADAS), helps alleviate driver fatigue. At the same time, many automakers and tech giants are beginning to test more advanced Levels 3 and 4 autonomous driving capabilities.

The hardware required for autonomous driving includes sensors such as radar, LiDAR, cameras, infrared, and ultrasonic sensors. The vehicle's onboard computer also needs a more powerful processor core. On the software side, a robust map system, AI algorithms, and extensive driving data are crucial. Additionally, for effective communication with the computer, smart vehicles must be equipped with interfaces such as touchscreens and voice recognition functionalities.

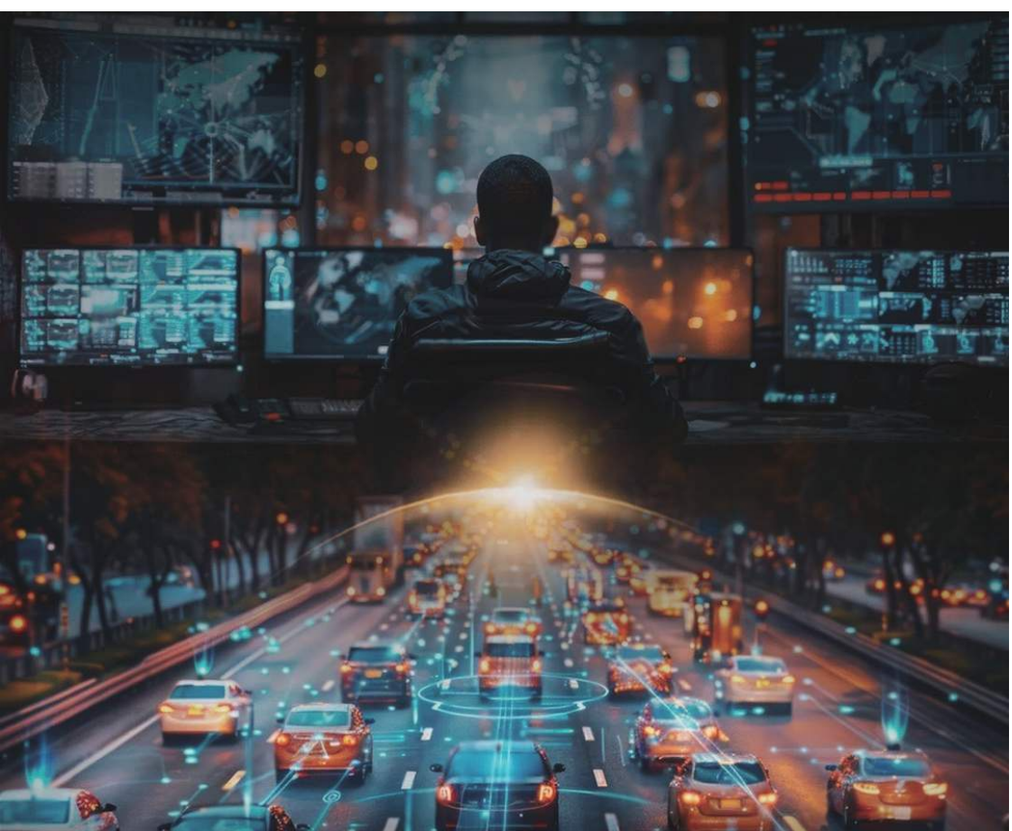
The development of autonomous driving goes beyond just the technology within the vehicle; equally important is external connectivity, known as "vehicle-to-everything" or V2X, such as V2V, V2I and V2P. This technology enables road

safety alerts, smart traffic signals and smart highways where trucks can drive in platoons. Integrating smart transportation, computers could coordinate the optimal lanes and speeds for each vehicle, ultimately achieving the ideal of zero accidents and zero congestion.

Building on the premise of connected vehicles, the broader vision for future mobility aims to expand into “mobility as a service” or MaaS—a seamless, integrated transportation system that allows users to plan and execute all their journeys through a single platform. This concept includes not just cars but also bicycles, scooters, motorcycles, buses, trams, boats, and airplanes. Overall, the goal of MaaS is to integrate all mobility needs to reduce costs and improve the efficiency of public transportation.

Gartner, a research and advisory firm, anticipated the market value of MaaS will increase to US$372 billion by 2026, up from US$42 billion in 2018. The main factor is that the transition towards smart transportation enables more complete and highly efficient mobility services.

Smart vehicles will continue to play a key role in future mobility. In Computex 2025, the Smart Mobility area features the Smart Mobility Pavilion curated by the Taiwan Advanced Automotive Technology Development Association (TADA). It will showcase smart mobility solutions offered by various service providers, including Solid State System Company and Elan Microelectronics Corporation. The solutions, such as V2X and autonomous driving technologies, will provide easier and safer journeys for travelers.



Pegaverse Yoda

Major Move of Focus for Next-Gen HMD Industry; Full Deployment in Lightweight AR Glasses Now Happening

Tech events at CES 2025 have showcased a plethora of new startups and well-known brands displaying next-gen augmented reality (AR) smart glasses this year. This further highlights the industry's gradual shift towards AI-assisted AR smart glasses amidst the limitations in new applications development and the continuous slowdown in shipment volumes for virtual reality (VR) and mixed reality (MR) devices.

Eric Chiou, Senior Research Vice President at TrendForce, stated that the VR / MR market has regressed in the past year compared to the year before. He anticipated that there will be a further slowdown in shipment volumes for VR and MR devices this year as Apple is said to have ceased the production of Vision Pro by the end of last year. In addition, a cheaper version of Vision pro or updated versions of Meta products will not be launched until 2026.

A report from the Ericsson ConsumerLab in May 2024, focusing on early adopters of AR, indicated that the number of users willing to use AR glasses in conjunction with smartphones is expected to double within the next five years. Users have a strong demand for portable AR glasses, and are even willing to pay 20% more for the convenience of having them on the go.

TrendForce projects the total shipment of AR devices in 2024 to be 700K units. With the integration of AI features, AR glasses are expected to receive a significant boost in momentum. Particularly, various global startups are aggressively launching a wide range of AI-assisted AR glasses, leading to an intense " Battle of AR Glasses " in the market. Driven by this enthusiasm, the market is expected to further expand to 25.5 million units by 2030 at an astounding CAGR of over 67%.

Cross-discipline Technology Integration Is Promoting Comprehensive Industry Restructuring in the Future

The smart mobility industry and the HMD industry are similar in terms of technology structure. They both rely on sensors, Near-Eye Displays (NED), automotive displays, High Performance Computing (HPC) chips and power modules. Taiwanese manufacturers and the semiconductor industry are at the intersection point of these supply chains. The biaxial technology revolution is not only about upgrading wheels and glasses, but it also redefines the way of living, the way a city works and industry logic. Revolving around five trusted industry sectors, the production sector and the academic sector in Taiwan promote technology integration of AR display and automotive electronics. With their result showcased in the military industry and the security control sector, a new trend of Made in Taiwan (MIT) production and technology strength can be expected to emerge after 2030.

Foxconn Chairman Young Liu announces AI data center with Nvidia

Young Liu, Chairman of Hon Hai Technology Group (Foxconn), delivered a keynote speech on May 20 at Taipei Nangang Exhibition Center Hall 2, announcing that it would build an artificial intelligence (AI) center with Nvidia targeted to have 100 megawatts of power in Taiwan.

At the event, Liu said the AI data center would be built in phases and would be located in Kaohsiung and some other regions of the country, depending on power availability.

"Power is a very critical resource in Taiwan. I don't want to use the word 'shortage'. It will take a few steps to reach 100 megawatts, starting with an initial phase of 20 megawatts," he said.

Nvidia's CEO Jensen Huang, appearing as Liu's special guest, reiterated that the AI factory to be built in Taiwan, announced earlier this week, was intended for use by Foxconn, Nvidia and Taiwan's entire ecosystem.

Huang also highlighted the two companies' collaboration spanning from AI agents for manufacturing inspection to a wide spectrum of robots, such robots orchestrating other robots and even robots building other robots.

Before Huang's surprise appearance, Liu announced Foxconn's partnership with TechOrange to establish Taiwan's leading robotics community, aiming to drive innovation and address the challenges posed by the GDP paradigm shift.

Young Liu
Chairman & CEO, Hon Hai Technology Group (Foxconn)

Elaborating on the paradigm shift, Liu said developed countries tend to have insufficient workers for low-pay jobs, and that would be where AI and robotics came in to fill the void, urging leaders of developed countries to pay close attention to the rapid advancement in AI when facing such demographic challenge.

Apart from hardware, Liu also announced FoxBrain, the company's developing foundation model that would be built on top of Nvidia's software stack, would support the company's new initiative.

The model would be specialized in reasoning, with deep understanding in specific numeric readings that most general AI models were not capable of, Liu said, adding that it would be made open-source to encourage the wider AI community to contribute to make it more powerful and useful.

The model's capability in reasoning would be required for the company's smart platforms applications, namely smart manufacturing, smart electric vehicles and smart city, that were part of the company's new initiative, Liu said.

The three intelligent platforms would be powered by AI factories, Liu said.

Envisioning future factories, he anticipated that the Omniverse digital twin factory would first be created, then came the AI factory to process the data from the former to create AI models, and finally the optimized physical factory that deployed and adapted the AI models would be constructed.

Liu said he believed that the demand for compute power would only continue to grow exponentially due to the proliferation of AI applications and the ongoing evolution of AI models.

MediaTek CEO Rick Tsai announces new 2nm chip to tape out in September

MediaTek Vice Chairman and CEO Dr. Rick Tsai delivered a keynote speech on "AI for Everyone: From Edge to Cloud" at COMPUTEX 2025 on May 20.

MediaTek is a "global leader in semiconductor solutions," with over 20 billion devices powered by MediaTek in the last decade, averaging 2.5 devices for every person on Earth.

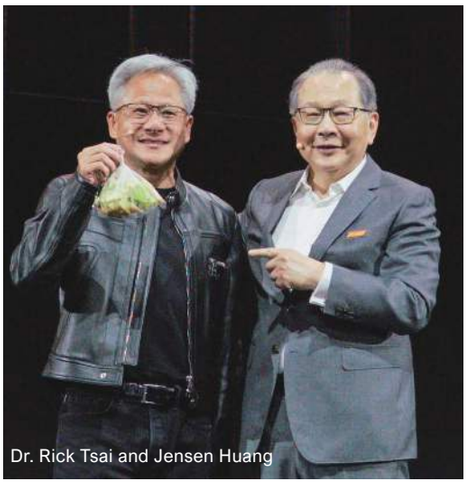
Following his COMPUTEX debut last year, Tsai used the keynote to outline MediaTek's "blueprint for a connected intelligent world," enriching lives from supercomputers to self-driving cars, data centers to our very own living rooms.

On Tuesday morning, Tsai unveiled MediaTek's "leap into 2-nanometer silicon innovation" with the first 2nm device set to tape out this September, delivering 15% better performance and 25% lower power consumption than the 3nm chip.

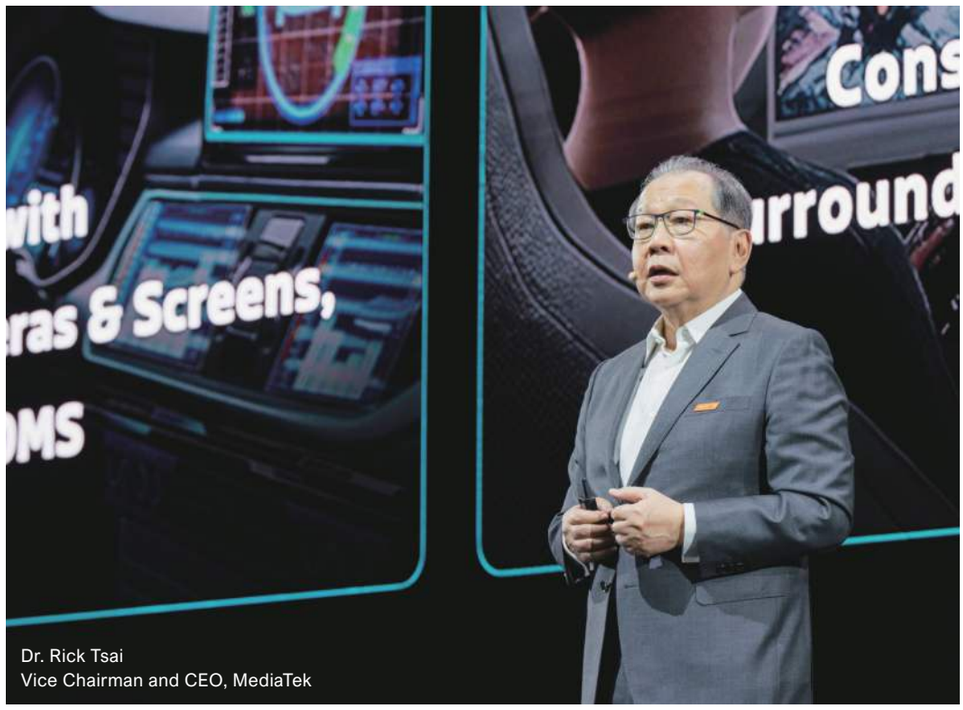
Tsai also stated MediaTek's plans to take a leading role in the advance towards 6G, which would "develop with AI at its core."

MediaTek outlined outstanding processing improvements, with CPU performance increasing over three-fold, GPU performance over seven-fold, and NPU performance accelerating by an impressive 29.1-fold since 2019.

A major focus of Tsai's keynote speech was MediaTek's partnerships with industry leaders to create a collaborative ecosystem. Tsai brought Nvidia CEO Jensen Huang on stage to elaborate on their joint project, the DGX Spark.



Dr. Rick Tsai and Jensen Huang



Dr. Rick Tsai
Vice Chairman and CEO, MediaTek

The 20 CPU core, compact supercomputer for cloud developers uses a MediaTek-designed GB10 Grace-Blackwell Superchip, offering "a Petaflop of AI performance on your desk," boasting a tensor performance of 1000 AI TOPS.

"MediaTek is incredible at collaboration," Huang said, praising a partnership with Tsai spanning four decades.

Tsai further highlighted MediaTek's Chromebook collaboration with Google, with the latest model delivering 50 TOPS of AI computing capability using the MediaTek NPU 890.

As the titular topic of Tuesday's keynote speech, Tsai outlined a future shaped by MediaTek's AI infrastructure.

From bringing online classrooms to the Korky tribe in India, to a futuristic simulation of AI-powered homes, the applications were seemingly endless for their vision of the "AI connected world;" one that is "coming very soon."

Tsai outlined MediaTek's portfolio of processors, starting with their mobile chips, which held the number one global smartphone chipset market share for the last 18 consecutive quarters and generated over $2 billion in revenue last year.

Their latest processor, the Dimensity 9400+, is capable of achieving crystal-clear mobile photography and utilizes independent agentic AI assistants without cloud latency.

"I guarantee you will see 9500, 9600 coming out every year, like a clock," Tsai said of future evolutions.

In the fast-developing automotive sector, MediaTek chips are set to enable AI across all auto-segments.

The Dimensity Auto Cockpit C-X1 flagship chip can offer an intuitive and interactive, safe and pleasant driving experience, featuring up to 12 simultaneous cameras and screens, in-car entertainment and AI assistants.

Described as an "extension of your home," this next-gen AI cockpit experience "will be working in a real car, real soon," Tsai said.

NVIDIA Cosmos Awarded the Best Choice of the Year

COMPUTEX TAIPEI, Asia's leading B2B ICT trade show, officially started yesterday at Taipei Nangang Exhibition Center Halls 1 and 2. As one of the organizers, the Taipei Computer Association (TCA) is proud to state that COMPUTEX serves as a major platform for global buyers and a focus of media attention. During the opening ceremony, the top award of the event, Best Choice of the Year, was awarded to NVIDIA Cosmos.

The judging panel highly commended NVIDIA Cosmos as the Best Choice of the Year. The platform boosts the development of physical AI, including robotics and autonomous driving, by introducing open and customizable inference models. It brings together advanced generative world foundation models, high-performance visual tokenizers, security protection mechanisms, and video processing pipelines to provide powerful tools for AI developers. The NVIDIA Cosmos Tokenizer can efficiently convert images and videos into computer-processable tokens for excellent performance boosts in both overall compression rate and processing speed.

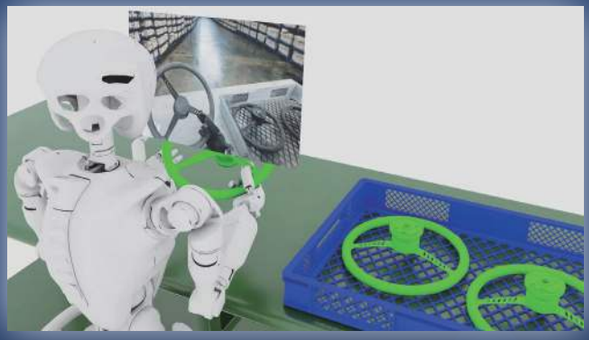
Winners of the Best Choice Award this year span various technological fields, including AI, gaming, cybersecurity, smart applications, and environmental sustainability, in alignment with procurement trends among international buyers.

The Best Choice Award 2025 demonstrates the technology industry's innovative momentum and commitment to sustainability. To enhance the award's visibility and attract greater attention from domestic and international buyers, all winning products will be displayed during COMPUTEX TAIPEI on the 4th floor lobby of TaiNEX 2. Global industry professionals are invited to join in witnessing the energy of technological transformation and our shared green future.

Detailed information and judges' comments for all winning products are published on the official Best Choice Award website.

https://bcaward.computex.biz/

Best Choice of the Year



NVIDIA
NVIDIA Cosmos
TaiNEX 1, 4F ► N1431

Golden Award

NVIDIA
NVIDIA Grace Blackwell 200 NVL72
TaiNEX 1, 4F ► N1431

Realtek
Ultra-Low-Power
Multimodal AI SoC
TaiNEX 1, 3F ► G0111

Best Choice of the Year Award

Awarded Product	Company
NVIDIA Cosmos	NVIDIA

Golden Award

Awarded Product	Company
NVIDIA Cosmos	NVIDIA
NVIDIA Grace Blackwell 200 NVL72	NVIDIA
Ultra-Low-Power Multimodal AI SoC	Realtek
Advanced GenAI Fine-tuning 6nm AI SSD Solution	Phison
Titan 18 HX Dragon Edition Norse Myth	MSI
Edge AI NB Touchpad with Accessibility Mode & Gesture	ELAN
AI@Edge Fanless Embedded AI System with NVIDIA® Jetson AGX Orin™	AAEON
DeCloakBrain AipA Robot System	Etron
ThreatVision	TeamT5

Sustainable Tech Special Award

Awarded Product	Company
Aspire Vero 16	Acer
TravelMate P6 14 AI	Acer
ROG Harpe II Ace Wireless Gaming Mouse	ASUS
Cubi NUC AI Series	MSI
T-FORCE DELTA RGB ECO DDR5 DESKTOP MEMORY	TEAMGROUP
i-Ctrl AirMaster	AIFA

Category Award

Awarded Product	Company
5G Generative AI Gateway	MediaTek
NVIDIA GeForce RTX 5090 GPU	NVIDIA
NVIDIA Quantum-X Photonics InfiniBand Switch Systems	NVIDIA
AIR-420 Edge AI Application Server	Advantech
Multi-Function High-Speed Wireless IC	Realtek
NVIDIA DGX Spark	NVIDIA
ASM4242 | USB4 Host Controller 40G	ASMedia
Enterprise Edge AI Switch IC	Realtek
Intel® Core™ Ultra 200V Series Processors	Intel
Edge-based Pedestrian AI Safety System	ELAN
AI-Stack	INFINITIX
aiDAPTIV+ One-stop GenAI Local Training Solution	Phison
AI enabled touch screen solution for IPC	ELAN
AORUS MASTER 16	GIGABYTE
EPD Solution Suite for Smart Logistics and Warehousing	Advantech
MEG VISION X AI	MSI
ROG Harpe II Ace Wireless Gaming Mouse	ASUS
Claw 8 AI+ A2VM	MSI
Swift Edge 14 AI	Acer
Dr. AI	Gemtek
ROG Strix ACE Series Gaming Monitor	ASUS
Edge Vision AI Traffic Signal Control	ELAN
Predator XB323QX Gaming Monitor	Acer
ROG Falcata Gaming Keyboard	ASUS
Enhanced Lane Assistance Navigator 3.0 (ELAN)	ELAN
Prestige 13 Ukiyo-e Edition	MSI
2025 ROG Zephyrus G14	ASUS
Medical Operating Room All In One Panel PC Solutions	Wincomm
MS633 Bluetooth 2D Ring Scanner	Unitech
INDUSTRIAL P250Q One-Click Data Destruction SSD	TEAMGROUP

Etron
DeCloakBrain AipA Robot System
TaiNEX 1, 4F ► M1203a

MSI
Titan 18 HX Dragon Edition Norse Myth
TaiNEX 1, 4F ► M0504

Phison
Advanced GenAI Fine-tuning 6nm AI SSD Solution
TaiNEX 1, 4F ► M0419a

TeamT5
ThreatVision
TaiNEX 2, 4F ► S1025a

AAEON
AI@Edge Fanless Embedded AI System with NVIDIA® Jetson AGX Orin™
TaiNEX 2, 1F ► P0214

ELAN
Edge AI NB Touchpad with Accessibility Mode & Gesture
TaiNEX 1, 4F ► N1013a

Artificial Intelligence Peripheral Development Possibly the Main Drive behind Future Technological Advancements

Talk of AI dominated discussions at the Taiwan External Trade Development Council (TAITRA)-hosted COMPUTEX 2025, one of the world's most extensive IT exhibits and a premier annual event for the global tech industry, and its attending exhibit for startup companies, InnoVEX 2025. Almost everything, in some form, was connected to the concept, from EdTech, medicine, online analyses, to EV charging, edge AI servers, and CPUs.

The recent development of ChatGPT and other AI software, and world governments' race to build data centers, further hyped up AI. But what is AI, and does it truly hold the key to the continued advancement of technology? How does a set of programming programs on a machine aim to accomplish such goals?

Consider that AI, at its base, is a set of programming code running on a machine. To function, it requires a significant amount of data to learn from, or Large Language Models, and would, in turn, output an astronomical amount of data, thereby necessitating the need for storage. Consider, too, that the machine in which the program is housed would require robust processing power to allow the code to process the data, which would require a staggeringly high amount of power to maintain and run.

These requirements in and of themselves fuel the development of peripheral and next-gen technology as we continue our quest to develop AI. Seagate, known for its data storage products, has answered the challenge by developing the Heat Assisted Magnetic Recording (HAMR) technology to ensure the increased data density stored on each storage disk, resulting in the same number of discs on a drive, but increased total data.

MSI's Autonomous Mobile Robots (AMRs), middle, being featured at the company booth #J0506 yesterday at Nangang Exhibition Hall 1

COMPUTEX 2025 participants visiting the Intel booth #J0306 yesterday at Nangang Exhibition Hall 1

Seagate rack-level servers being displayed at the Seagate booth #K1201 yesterday at Nangang Exhibition Hall 1

Intel, the CPU giant, acknowledged that AI is a continuing trend that will see further development over recent years. When asked what it was doing to not just be a passive trend follower, but what it could do to define, or set, the trend, Intel said it is doing its best in developing hardware that would be ready for the public when AI use is more widely accepted.

As a producer of both CPUs and GPUs, Intel recognizes that the edge GPUs have over CPUs in AI processing won't be going away soon, and stated instead that the company considers the main challenge ahead to be how to harness the processing power of both CPUs and GPUs to process AI algorithms.

Similarly, MSI is developing rack-level edge AI, or the direct deployment of AI models on local edge devices for real-time data processing and analysis without reliance on cloud servers, with a focus on industrial applications, which again highlights how the development of AI technology drives companies and other technologies to keep pace.

NVIDIA Inception Startups Aim for Sustainability and AI Applications

The NVIDIA Inception Startup Pavilion at Innovex 2025 featured a whopping 16 startup companies, spanning the fields of AI, robotics, transportation, medical and manufacturing automation.

Nanyang Biologics' Drug-Target Interaction Graph Neural Network (DTIGN) can enhance the discovery of new drugs, while FindingsTech's HepatiticWell.ai and Deeli AI's innovative platforms help increase the accuracy and efficacy of diagnoses.

Also featured at Nvidia's startup pavilion are AIRECO, which offers automated recycling solutions – utilizing AI programming to enable machines to identify bottle types and smooth recycling procedures –

and Avalanche Computing, which provides corporations with intelligent automation during manufacturing.

NVIDIA Inception Startup Pavilion

POD Innovation is showcasing an advanced warning system for possible forward-motion collision for light rail trains, while Lynx Analystics hopes to use its 2000:MM platform to better enable corporate understanding of market trends.

Morale AI, MetAI, and Futurenest contribute to developing AI and Large Language Models, while Avalanche Computing and APMIC are also developing high-efficiency computation and amelioration of AI models so that the corporate sector would have more efficient AI functions.

AeiRobot

The NVIDIA Inception Startup Pavilion at the 2025 InnoVEX seeks to indicate the newest results from global startup companies in terms of AI development and computational power, and hope that through the Nvidia Inception Startup Pavilion, these companies can expedite the maturity of their system, seek broader markets, and showcase their innovation to the world.

NVIDIA INCEPTION STARTUP PAVILION
► **S0724** | TaiNEX 2

French Startups Tout Sustainability and Human-Machine Dealings

The French Pavilion, organized by La French Tech and Business France, at the 2025 InnoVEX at the Taipei Nangang Exhibition Halls 1 and 2 on May 20 and goes through May 23, saw the return of six companies featuring products on the naturalization of human-machine interaction, a focus on sustainability and "green energy," and deep tech capabilities.

Dracula Technologies, with its LAYER organic photovoltaic (OPV) technology converting ambient light to power low-power indoor Internet of Things (IoT) devices or other applications, as well as ITEN's cobalt and heavy solvent-free solid-state lithium micro-batteries, highlights French companies' continued focus on sustainability.

Similarly, Iten's microbatteries, aiming to provide power and energy density, and Dracula's OPV tech, underscore French companies' moving away from traditional software as a service business model and developing deep tech capabilities.

French Pavilion

In terms of facilitating human-machine interaction, Advanced Magnetic Interaction's (AMI) patented Gradient Magnetostatic Sensing technology seeks to, according to AMI sales manager Denis Matias, reinvent the workspace and bridge the digital and analog.

The technology comes in different forms — a strip that can be attached almost anywhere, from walls, tables, glass panels, to interactive displays — and pads with inbuilt functions that would facilitate user actions during meetings, such as zooming in, making notes, or using the stylus as a pointer.

Nanomade Labs' ultra-thin and flexible sensors, used on automobile dashboards and smart chairs, can detect touch, force, and deformation on any surface, even metal, and are fully customizable, with durability guaranteed.

FRENCH PAVILION ► S0116 | TaiNEX 2

Starcrossed Czech Startups Rapt on Industrial and Vertical AI

The 2025 InnoVEX, the annual startup exhibition held concurrently with COMPUTEX Taipei, this year features eight top Czech startups at the Czech Pavilion, organized and promoted by CzechInvest, the Czech Economic and Cultural Office, and the innovation ecosystem platform Startup Kitchen, covering fields such as artificial intelligence (AI), smart manufacturing, digital applications, automation, space technologies, and robotics.

Czech pavilion

Inovec Technology brings to the table this year the Dynamic Virtual Sensor that allows “highly flexible” collection of “easily interpretable data” from manufacturing, providing owners with better insightof the factory floor, while Robo Twin brings no-code robotics to the manufacturing industry, allowing workers to “teach” robots, without any prior knowledge of programming.

Czech companies have developed vertical AI, or AI used for vertical-specific use cases, such as Cognivibe’s AI-powered mental performance tracker, coaching workers to improve focus, reduce fatigue and boost productivity; Kompenzo’s “risk-free” claims management system, which uses a regulation-compliant business model on a no-win, no-fee basis, to make rightful compensation claims for personal injury more accessible to the majority of people; and PalmApp’s workforce system utilizing internal AI platforms to facilitate corporate communication internally.

RoboTwin s.r.o

Czech startups are turning their eyes to aerospace development, with Stellar Exploration developing advanced space subsystems such as high-performance batteries, power control and distribution units (PCDU) and scalable electric power systems (EPS), while Xtend Design provide space and tech companies comprehensive architectural, products, graphis, web, and branding designs.

CZECH PAVILION
► **S1023 / S0924b** | TaiNEX 2

Burgeoning Thai Startups Focus on Practical Applications for AI Tech

The 2025 InnoVEX, the annual startup exhibition held concurrently with COMPUTEX Taipei, included the Thailand Pavilion, organized by the Thai Department of International Trade Promotion and the Digital Economy Promotion Agency, to promote and support Thai startups and entrepreneurship ecosystems.

The 17 startups featured at the pavilion highlighted Thailand’s focus on health and genetics, practical Artificial Intelligence (AI) applications, cutting-edge innovative technology applications based on smell and other senses, and EdTech focusing on helping Thai schools transition to digital education.

Thailand Pavilion

MoveMax, for example, applies Artificial Intelligence (AI) to its Transportation Management System (TMS) and its Vehicle Routing Planning (VRP) systems on cloud platforms, while Wang uses AI to conduct market research, find target client groups based on user-defined criteria, or enlist other Internet users to support and supply data for AI language training.

Wang co-founder Krit Cangwanpongpun said that the information or services provided by the platform’s crowd source contributors are vetted via multiple means, including an interna lly-developed AI algorithm.

Thai startups are interested in developing products and technologies that demonstrate cutting-edge innovativeness, such as MUI Robotics, which has developed the MUI Nose, which is currently predominantly in the food industry, with plans to be adopted for medical use.

Student Care Company Limited provides core services, such as its school management

MUI Robotics

solution, allowing school faculty to create more appropriate consultation for students by monitoring their behaviors, and help foster students' interests.

On the medical front, GeneusDNA offers an extensive DNA analysis, over 20 categories and 500 items inspected, by collaborating with top-notch laboratories from the US, while providing clients easy access to the reports through the company’s self-developed application or its websites.

THAI PAVILION ► **S0917** | TaiNEX 2

ADVANTECH

Edge Computing & WISE-Edge in Action | COMPUTEX 2025

Hall 1, Booth #K0605 Advantech Branding Pavilion

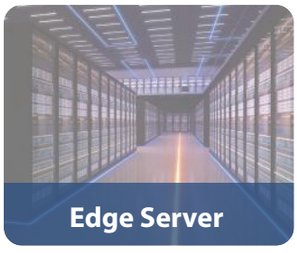
At COMPUTEX 2025, we will showcase Edge Intelligent Systems, Edge Orchestration & AI Agent, and Key Industries, featuring ten domain topics, from platform integration to Edge Computing and Edge AI services, driving safety, efficiency, and intelligence across industries.

What to Expect at the Branding Pavilion

Showcase Highlights

WISE-Edge

Edge Orchestration Platform

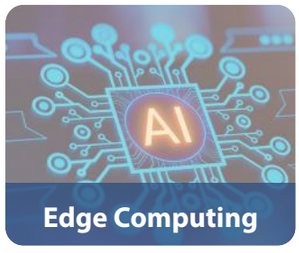


Edge Server

SKYRack–Industrial Full Rack Solutions

Autonomous Systems & Robotics

Beyond Automation: The Next Era of AI-Powered Robotics



Edge Computing

Leading Edge Computing Platforms & Solutions

Vision Intelligence

AI-Powered Vision Computing: Accelerating Digital-Physical Integration

Smart Factory

AI-Enabled Smart Manufacturing

Energy Management

Advantech iEMS AI+ Empowers Enterprises in Low-Carbon and Digital Transformation

iHealthcare

Empowering Healthcare with Edge Computing and iHospital Solutions

Environment

Ensuring Slope Safety through Smart Monitoring

Agriculture

AI Smart Farrowing Solution

Hall 2, Booth #P0413a iRetail & Smart City Pavilion

Join us at TaiNEX 2, 1st Floor, for Advantech's latest AI-driven innovations in smart services. The showcase also marks the first Asia presentation of Advantech-AURES solutions, featuring stylish POS and self-service products renowned in the European market.

Our exhibition features modular, easy-to-maintain product designs that enable seamless integration and operational efficiency across five key focus areas:

- iRetail & Kiosk Solutions
- Vision AI & Consumer Insights
- iLogistics & Cold Chain
- Energy & Utility Management

Experience three major AI-powered innovations:

- Self-Service with AI
- Analysis with AI
- Safety with AI

Event Site

BXB Showcases Ultra-Light DECT Wireless Microphone System

BXB introduces a DECT-based wireless microphone system designed to meet the demands of modern teaching and training environments. Operating on the exclusive 1.9GHz DECT band, the system avoids interference from 2.4GHz channels such as Wi-Fi and Bluetooth, delivering stable, high-quality voice transmission across up to 75 meters—ideal for multi-room and hybrid classrooms.

Supporting up to 30 microphones with zero conflict, the system enables real-time, multi-speaker communication, making it ideal for group discussions and corporate training. Each microphone weighs just 37 grams and offers multiple wearing modes—neck-worn, handheld, or clip-on—for maximum comfort and mobility. CD-quality audio streaming via Bluetooth 5.1 and support for headset connections further enhance its versatility.

A built-in MIC CALL emergency alert links to broadcast systems for instant safety response.

Additional features include AES-256 encryption for secure transmission, independent volume control with auto memory, and fast infrared pairing. Powered by USB-C charging, each unit delivers up to 8 hours of continuous use.

With its seamless integration of audio clarity, wireless freedom, and intelligent safety features, BXB's DECT microphone system redefines how educators and professionals communicate—delivering performance, reliability, and peace of mind in every space (know more: https://www.bxbsystem.com/dect-digital-wireless-microphone/).

BXB ELECTRONICS CO., LTD.

- www.bxb.tw
- **K0828** | TaiNEX 1

ARES Q4 USB4 MagSafe Portable SSD

Redefining storage with exceptional speed and portability—designed for the modern era.

The ARES Q4 MagSafe Portable SSD is a game-changer for modern storage needs, combining speed, convenience, and versatility in a compact device. Designed to empower creative professionals and tech enthusiasts, it features USB4 Gen3x2 technology with blistering read speeds of up to 4000MB/s and write speeds of up to 3600MB/s, ensuring seamless data transfer and efficient workflows.

At just 40 grams, its ultra-lightweight design and MagSafe compatibility make it the perfect companion for iPhone 15 PRO and newer users, offering secure attachment and effortless portability. This device unlocks your phone's full potential by providing an impressive 4 TB of storage—ideal for continuous ProRes video recording, enabling creators to capture every moment without worrying about space.

With 40 Gbps super-fast transmission, the ARES Q4 eliminates delays and enhances productivity, whether you're transferring large files or accessing data on the go. Its USB Type-C connectivity supports instant plug-and-play across a variety of devices, making it a versatile tool for both professional and everyday use.

Streamlined and innovative, the ARES Q4 MagSafe Portable SSD is the ultimate solution for those who demand high-performance storage and portability. It's the ideal way to expand your digital capacity while maintaining exceptional speed and convenience. Take your storage experience to the next level!

DATOTEK INTERNATIONAL CO., LTD.

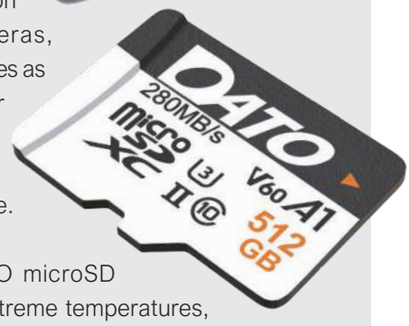
- ▶ www.datos.com.tw
- ▶ **J0327a** | TaiNEX 1

DATO microSD Express SD7.1

Compact Excellence with High-Speed PCIe and NVMe Performance.

The DATO microSD Express redefines storage with outstanding speed and reliability. Utilizing the SD7.1 UHS-I standard along with PCIe Gen3x1 and NVMe interfaces, it achieves read speeds up to 800MB/s and write speeds up to 700MB/s, surpassing many SATA SSDs by 1.5 times and outperforming UHS-I cards by over 8 times.

Designed for versatility, it supports gaming consoles, action cameras, drones, 360° cameras, AI-driven IoT applications, and serves as a portable SSD alternative. Whether for dynamic video capture or demanding data processing, it ensures exceptional performance.



Built for durability, the DATO microSD Express is resistant to water, extreme temperatures, shock, and X-rays, providing reliable protection for data in tough conditions. Compact yet powerful, it is the perfect choice for users seeking fast, efficient, and resilient storage. With DATO microSD Express, experience innovation that keeps pace with your digital demands.

PHISON

PASCARI

Engineering Imagination, Together

Phison is the world's leading private-label supplier of controllers and SSDs for enterprise and hyperscale storage, cloud and edge computing, and data centers.

The most sophisticated enterprise environments trust Phison for performance, capacity, endurance, and power efficiency.

Find Out More

PHISON 25 Years

PHISON

aiDAPTIV+

Extends GPU Memory

Making AI Processing on-premises Achievable for Organizations of All Sizes

Data Ingest → RAG → Fine Tune → Monitor → Validate → Inference

☑ Affordable ☑ Private ☑ Smarter AI

See How It Works

Ficer Technology Sets the Stage for the Future of Ai Networking at COMPUTEX TAIPEI 2025

FICER Technology Co., Ltd., a Taiwan-based leading vendor in fiber optic innovations, will present its latest optical networking solutions at COMPUTEX TAIPEI 2025. The showcase features high-capacity OTN DWDM platforms, next-generation Optical Transceivers, and High Speed Cabling products designed for AI, cloud, and next-gen data infrastructure.

Engineered for the demands of AI data centers and hyperscale networks, FICER's new products deliver faster connectivity, flexible deployment, and superior power efficiency to drive digital transformation across industries.

At the forefront of FICER's exhibit is the OTN DWDM Transmission Platform, a high-capacity solution designed to support large-scale fiber optic networks. With its modular architecture and exceptional scalability, the platform enables long-distance WDM transmission with minimal operational overhead—making it a compelling choice for internet data centers (IDCs), internet service providers (ISPs), and enterprise core networks.

Enhancing this system's performance is the new DWDM 1U Stand-alone EDFA—a Low cost erbium-doped fiber amplifier engineered for optical signal amplification with high stability and low noise. Compact and easily deployable, this 1U unit is tailored for metro and long-haul networks that demand consistent signal quality over extended distances.

FICER also introduces the DWDM C-Band EDFA Module, delivering low-degradation signal amplification for DWDM networks. Optimized for extended-range transmission, this module strengthens system performance and ensures reliable data delivery in high-demand environments.

To meet the bandwidth needs of AI and compute-intensive applications, 800G Optical Transceivers (OSFP and QDD112-DD), offering ultra-high data rates and superior energy efficiency. Additionally, the 400G Optical Transceivers (QSFP112 and QSFP56-DD) provide optimized, low-latency connectivity for next-generation data centers seeking scalable throughput.

For coherent optical transmission across metro and long-haul networks, FICER offers the 400/200/100G CFP2 DCO and 400G QSFP56-DD DCO Transceivers, enabling secure, high-speed data transport across complex network topologies with unmatched flexibility and reliability.

In dense and space-limited deployments, FICER's 40G/100G BiDi Transceivers provide compact, bidirectional communication that maximizes fiber utilization and minimizes infrastructure cost—perfect for high-density cloud and enterprise networks.

Completing its product lineup, FICER delivers a range of Active Optical Cables (AOC), Direct Attach Cables (DAC), and Active Electrical Cables (AEC) to provide low-latency, high-bandwidth connections between switches, routers and servers. These cabling solutions offer high integration, energy savings, and optimized performance for complex and demanding data environments.

With those products, FICER underscores its commitment to advancing intelligent digital infrastructure through cutting-edge optical technologies, supporting customers worldwide in navigating the next wave of AI-driven transformation.

About FICER

Founded in 2005, FICER is committed to innovation and delivering professional, prompt, and secure fiber optical products that empower customers to stay competitive in the rapidly evolving AI and data technology landscape. With over 20 years of experience, the company offers design, manufacturing, and tailored value-added services, emphasizing quality, innovation and satisfaction for customers.

FICER TECHNOLOGY CO., LTD.

- www.ficer.com
- **K1027a** | TaiNEX 1

Supermicro's Max Performance X14 Servers and New H14 3U System

Extra Flex with X14 Systems, Featuring Intel® Xeon® 6 Processors, Optimized for Performance and Efficiency to Accelerate Any Workload

The Supermicro X14 range of servers is the highest performing, most flexible ever, based on platforms proven over several generations and deployed in some of the world's largest data center installations. From large-scale AI Training and Generative AI to scale-out data centers and the intelligent edge, Supermicro X14 systems are based on modular Building Block Architectures with hybrid support for the entire range of Intel Xeon 6 processors, offering complete customization and optimization for any workload. With Supermicro's complete rack-scale integration services, liquid cooling solutions, and industry-leading global manufacturing capacity, X14 serves as the foundation for total IT solutions at any scale – from a single system to a multi-rack cluster.

Supermicro X14

What's New in Supermicro X14

- Featuring Intel® Xeon® 6 Processors
- Higher core count for greater compute density
- Faster memory bandwidth and new capabilities to extend capacity
- EDSFF E1.S and E3.S NVMe support
- Data Center Modular Hardware System (DC-MHS) support

Designed and Optimized for Various Applications

- Large-scale AI, HPC, and media
- High-density HPC and AI
- High-performance enterprise and cloud
- Enterprise and cloud data center
- High-density cloud
- Edge and telco
- Storage

Learn more:
https://www.supermicro.com/en/products/x14

Supermicro MicroCloud 3U Multi-Node Server

Supermicro MicroCloud 3U Multi-Node Servers Powered by AMD EPYC™ 4005 processors

The new MicroCloud 3U multi-node servers are designed and optimized for higher density, scalability, and affordability. Built on Supermicro's proven building-block architecture, the servers can help data centers efficiently scale and deliver to Server Message Block (SMB). More about the new MicroCloud servers:

Unparalleled density on a 3U form factor: Supermicro servers feature AMD EPYC™ 4005 processors deliver maximum density, with options to support AMD's 3D V-cache technology to deliver better performance and higher compute density.

- Maximum energy efficiency and affordability: Supermicro's latest MicroCloud 10-node and 5-node support AMD EPYC™ 4005 with highly efficient Zen 5 processor core.
- Trusted AI solution for hosted service & SMB: Designed for enterprise customers and hosted IT services providers that demand performance, advanced technologies.

More Supermicro Servers Based on AMD's Powerful Chips

Supermicro's all-new redesigned H14 generation solutions offer unparalleled performance and flexibility for a wide range of AI and HPC applications, helping enterprise customers efficiently upgrade and scale their workloads. Supermicro offers one of the broadest portfolios of AMD EPYC™ servers, featuring the latest EPYC 9005 series processors to provide maximum core count, density, and efficiency.

The H14 generation servers also support the latest leading GPUs including the new AMD Instinct™ MI325X. With the combination of the latest EPYC CPU and Instinct accelerators, the H14 servers truly offer a powerhouse of AI-enabled solutions to the global market.

SUPER MICRO COMPUTER, INC.

► www.supermicro.com

► **N0605a** | TaiNEX 1

Thermaltake Expands Future Dusk Color Option to Chassis Models

Thermaltake, a leading PC DIY brand for premium hardware solutions, is proud to announce the expansion of its distinctive Future Dusk colorway to three additional chassis series: the TR100, View 380 XL, and View 390 Air. Following the remarkable success of the Tower 600 Future Dusk Edition, this bold and futuristic aesthetic is now making its mark across more of Thermaltake's signature chassis lineup, perfectly suited for both large and small chassis.

Future Dusk is a striking blend of metallic blue and soft purple tones, finished with a subtle, light-reactive shimmer. Drawing inspiration from cyberpunk visuals and forward-thinking design, it offers a modern, eye-catching look that sets your setup apart, perfect for creators, gamers, and tech enthusiasts who want their build to stand out as much as it performs.

These new additions bring together Thermaltake's renowned chassis design with an elevated sense of style. The TR100, with its SFF footprint and sleek profile, takes on a whole new personality in Future Dusk. The View 380 XL, and View 390 Air, known for their expansive tempered glass panels that provide a great view, now feature an exterior that is as immersive and impressive as the internal components they showcase.

By bringing Future Dusk to these fan-favorite models, Thermaltake continues its commitment to blending high performance with bold, innovative design. Whether you're building a high-powered gaming system or a centerpiece for your workspace, the Future Dusk chassis collection delivers both functionality and a fresh, futuristic take on modern PC aesthetics.

Experience the color of tomorrow — now available across more Thermaltake chassis.

THERMALTAKE TECHNOLOGY CO., LTD.

- www.thermaltake.com
- **N0102** | TaiNEX 1

MiTAC Computing

Empowering Data Centers of Tomorrow

COMPUTEX Booth #M1110

Uncompromising Quality through Rigorous Methods

Energy-Efficient and Sustainable Innovation

Comprehensive Portfolio with Customization Capabilities

Trustworthy Global Service Networks

Visit Our Website

MiTAC Computing

Meet the Heroes

Explore MiTAC Computing's latest innovations in AI inference, high-performance computing, cloud infrastructure, and enterprise workloads—featuring firsthand insights into our cutting-edge server technologies.

AI Inference

G4527G6 – Scale-out GPU Platform by NVIDIA MGX™

Easily upgrade, swap, and scale with a modular server that extends product life, simplifies maintenance, reduces costs, and enables flexible innovation across your ecosystem.

- **Scale-out GPU clusters for AI**
- **Integrated NVIDIA ConnectX-8 SuperNIC**

G8825Z5 – Built for AI at Scale

A powerful server designed for large-scale AI and HPC applications with exceptional memory capacity – ideal for scientific simulations, developing cutting-edge AI & ML models, or big data analysis.

- **8 AMD Instinct™ MI350 Series GPUs and platforms**
- **ROCm™ open software stack**

High-performance Computing

G4520G6 – GPU-accelerated HPC Server

A powerful server built for AI, HPC, and data-intensive workloads, supporting a wide range of applications such as edge AI and IoT, finance and risk analysis, healthcare and life sciences, cybersecurity and blockchain, as well as education and research.

- **Up to 8 dual-slot GPUs for AI and HPC**
- **Flexible GPU configurations**

TN85-B8261 – Optimized for Demanding Compute

A versatile HPC server designed for high-performance computing and the most demanding computational tasks including AI, data analytics, virtualization and cloud computing, as well as media and entertainment.

- **2S AMD EPYC 9005/9004 CPU**
- **24 DIMM slots with DDR5 6400 memory support**

Cloud Infrastructure

M2810Z5 – Power-Efficient CSP Server

A high-density, multi-node server built for CSP micro-service deployment. Scale effortlessly with up to 192 computing cores per node for maximum performance in cloud-native environments.

- **Multi-node**
- **High core count**
- **Up to 192 computing cores per node**

Enterprise Workloads

R2520G6 – Mainstream Enterprise Server

A powerful, ultra-fast, and easily upgradable server that offers unparalleled compute and storage capabilities, making it ideal for ERP, SCM, and business intelligence applications.

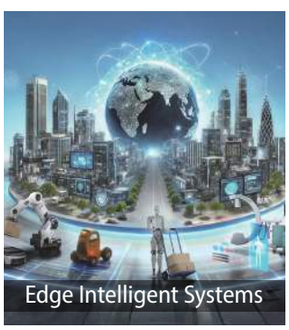
- **DC-MHS modular architecture**
- **DC-SCM v2.0 secure control module**

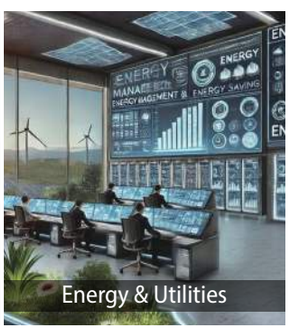
ADVANTECH

Edge Computing & WISE-Edge in Action

COMPUTEX 2025

In-depth exploration of how edge computing and WISE-Edge are revolutionizing industries and driving real-world innovation. We bring together global partners and industry leaders to uncover breakthrough insights, showcasing innovations that are responding to market trends and leading advancements across five key domains worldwide.


Edge Intelligent Systems



Energy & Utilities


Manufacturing


iHealthcare


iCity Services & iRetail

3 Key Themes, 15 Solution Highlights, 24 Industrial Insights:
The Complete Advantech Experience

Branding Pavilion & Insight Studio
May 20-23 @ Taipei Nangang Exhibition Center Hall 1, 1F, K0605

iRetail & Smart City Pavilion
May 20-23 @ Taipei Nangang Exhibition Center Hall 2, 1F, P0413a

COMPUTEX Forum: Robotics & Edge AI
May 21, 11:30~12:00 @ Taipei Nangang Exhibition Center Hall 2, 7F

Visit Advantech COMPUTEX Event Site for New Insights!

Watch Edge Computing & WISE-Edge in Action on Advantech YouTube!